same as those described in the first embodiment.

[S4011]

Step S4011 is the same as that described in the fifth embodiment.

[S4013]

Steps S3012 and S2013 to S2016 are the same as those described in the third embodiment.

<6> Sixth Embodiment

Next, the sixth embodiment is described. In the sixth embodiment, an example where a memory system comprises a structure which allows a manufacturer to check with the naked eye which memory chip 100 is operating is described. Descriptions of portions similar to those of the foregoing embodiments are omitted. The sixth embodiment can be combined with the first to fifth embodiments.

<6-1> Configuration of Package

Next, a configuration example of the package 11 according to the sixth embodiment is described with reference to FIG. 31. FIG. 31 is a block diagram showing an example of a configuration of a package 11 according to the sixth embodiment. For easy understanding, only one package 11 is explained with reference to FIG. 31.

As shown in FIG. 31, a plurality of memory chips 100 included in the package 11 are stacked in a stepwise manner. Furthermore, the plurality of memory chips 100 are arranged in such a manner that a plurality of pads (ten pads in FIG. 31 for simplification) that are arranged on the